



RoHS Compliant

**MAX  
260°C**

**MSL  
1**



PRODUCT FAMILY	Material	CAS Number	% Normalize for BOM	Wt. Of BOM Item (g)	% by Wt (Comp. Item)	mg/unit	% by Wt Of Unit 266.00	ppm
<b>767 16</b>								
Alumina Ceramic	Al2O3	1344-28-1	0.8750	0.2328	87.50%	203.6563	76.56%	765625
	SiO2 (silicon dioxide)	14808-60-7			12.50%	29.0938	10.94%	109375
Conductor Thick Film	Ag	7440-22-4	0.0059	0.0016	<b>100.00%</b>	<b>232.7500</b>		
	Pd	7440-05-3			99.00%	1.5537	0.58%	5841
Resistor Thick Film					1.00%	0.0157	0.01%	59
					<b>100.00%</b>	<b>1.5694</b>		
	RuO2	12036-10-1	0.0074	0.0020	30.00%	0.5905	0.22%	2220
	PbO	1317-36-8			10.00%	0.1968	0.07%	740
Notch Conductor Thick Film	SiO2 (silicon dioxide)	14808-60-7			30.00%	0.5905	0.22%	2220
	B2O3	1303-86-2			30.00%	0.5905	0.22%	2220
					<b>100.00%</b>	<b>1.9684</b>		
Lead Wire	Ag	7440-22-4	0.0112	0.0030	72.02%	2.1456	0.81%	8066
	Pd	7440-05-3			4.20%	0.1251	0.05%	470
	Pt	7440-06-4			23.78%	0.7085	0.27%	2663
					<b>100.00%</b>	<b>2.9792</b>		
Lead Under-Plating	Cu	7440-50-8	0.0360	0.0096	100.00%	9.5760	3.60%	36000
Solder					<b>100.00%</b>	<b>9.5760</b>		
	Ni	7440-02-0	0.0100	0.0027	100.00%	2.6600	1.00%	10000
Covercoat					<b>100.00%</b>	<b>2.6600</b>		
	Ag	7440-22-4	0.0360	0.0096	3.00%	0.2873	0.11%	1080
	Cu	7440-50-8			0.50%	0.0479	0.02%	180
	Sn	7440-31-5			96.50%	9.2408	3.47%	34740
					<b>100.00%</b>	<b>9.5760</b>		
Covercoat	TiO2	13463-67-7	0.0185	0.0049	50.00%	2.4605	0.93%	9250
	Phenolic Resin	55185-45-0			25.00%	1.2303	0.46%	4625
	Epoxy Resin	25068-38-6			25.00%	1.2303	0.46%	4625
		Sum	1.0000	0.2660	<b>100.00%</b>	<b>4.9210</b>		
			part weight	0.2660				
		<b>Totals:</b>		<b>0.2660</b>		<b>266.00</b>	<b>100.00%</b>	<b>1000000</b>

RoHS exemption claimed for lead in glass of electronic component